

DS2003 High Current/Voltage Darlington Drivers

Check for Samples: DS2003

FEATURES

- Seven High Gain Darlington Pairs
- **High Output Voltage (V_{CE} = 50V)**
- High Output Current ($I_C = 350 \text{ mA}$)
- TTL, PMOS, CMOS Compatible
- **Suppression Diodes for Inductive Loads**
- **Extended Temperature Range**

DESCRIPTION

The DS2003 comprises seven high voltage, high current NPN Darlington transistor pairs. All units feature a common emitter and open collector outputs. To maximize their effectiveness, these units contain suppression diodes for inductive loads appropriate emitter base resistors for leakage.

The DS2003 has a series base resistor to each Darlington pair, thus allowing operation directly with TTL or CMOS operating at supply voltages of 5.0V.

The DS2003 offers solutions to a great many interface needs, including solenoids, relays, lamps, small motors, and LEDs. Applications requiring sink currents beyond the capability of a single output may be accommodated by paralleling the outputs.

Connection Diagram

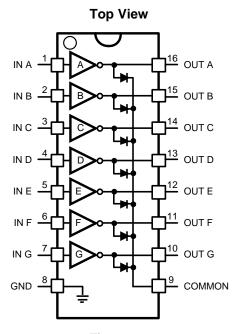


Figure 1.

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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings (1)(2)

Absolute Maximum Natings					
Storage Temperature Range	−65°C to +150°C				
Operating Temperature Range, T _A					
DS2003T	-40°C to +125°C				
DS2003C	-40°C to +85°C				
Junction Temperature Range, T _J	-40°C to +150°C				
Lead Temperature					
Soldering, 10 seconds	265°C				
ESD Ratings					
Human Body Model	+/-2000V				
Machine Model	+/- 200V				
Package Thermal Dissipation Ratings					
NFG0016E Package θ _{J-A}	88°C/W				
D0016A Package θ _{J-A}	115°C/W				
Input Voltage	-0.3V to 30V				
Output Voltage	55V				
Emitter-Base Voltage	6.0V				
Continuous Collector Current	500 mA				
Continuous Base Current	25 mA				

[&]quot;Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be specified. They are not meant to imply that the devices should be operated at these limits. The Electrical Characteristics provide conditions for actual device operation.

Electrical Characteristics

 $T_{\Delta} = 25^{\circ}C$, unless otherwise specified ⁽¹⁾

	Parameter	Test Conditions	Min	Тур	Max	Units	
I _{CEX}	Output Leakage	T _A = 25°C, V _{CE} = 50V (Figure 6)			20	μΑ	
	Current	T _A = 85°C, V _{CE} = 50V (Figure 6)			100		
		T _A = 125°C, V _{CE} = 50V (Figure 6) for DS2003T			150		
V _{CE(Sat)}	Collector-Emitter	$I_C = 350 \text{mA}, I_B = 500 \mu \text{A (Figure 8)}^{(2)}$		1.25	1.6	V	
	Saturation Voltage	$I_C = 200 \text{mA}, I_B = 350 \mu \text{A (Figure 8)}$		1.1	1.3		
		$I_C = 100 \text{mA}, I_B = 250 \mu \text{A (Figure 8)}$		0.9	1.1		
I _{I(ON)}	Input Current	V _I = 3.85V (Figure 9)		0.93	1.35	mA	
I _{I(OFF)}	Input Current	I _C = 500μA (Figure 10)	50	100		μA	
		T _A = +25°C	50	100			
		T _A = +85°C	25	50			
		T _A = +125C for DS2003T	10	25			
V _{I(ON)}	Input Voltage	V _{CE} = 2.0V, I _C = 200mA (Figure 11)			2.4	V	
	(4)	V _{CE} = 2.0V, I _C = 250mA (Figure 11)			2.7		
		V _{CE} = 2.0V, I _C = 300mA (Figure 11)			3.0		
Cı	Input Capacitance			15	30	pF	
t _{PLH}	Turn-On Delay	0.5 V _I to 0.5 V _O			1.0	μs	
t _{PHL} Turn-Off Delay		0.5 V _I to 0.5 V _O			1.0	μs	

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If Military/Aerospace specified devices are required, please contact the TI Sales Office/Distributors for availability and specifications.

All limits apply to the complete Darlington series except as specified for a single device type. Under normal operating conditions these units will sustain 350 mA per output with $V_{CE\ (Sat)} = 1.6V$ at $70^{\circ}C$ with a pulse width of 20 ms and a duty cycle of 30%.

The I_{I(OFF)} current limit ensured against partial turn-on of the output.

The $V_{I(ON)}$ voltage limit ensures a minimum output sink current per the specified test conditions. (4)



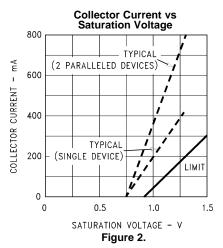
Electrical Characteristics (continued)

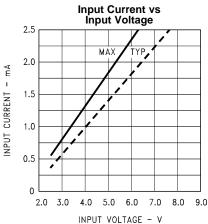
 $T_A = 25$ °C, unless otherwise specified ⁽¹⁾

	Parameter	Test Conditions	Min	Тур	Max	Units
I_R	Clamp Diode	V _R = 50V (Figure 12)				μA
	Leakage Current	$T_A = 25^{\circ}C$		5	10	
		$T_A = 85^{\circ}C$		10	50	
		$T_A = 125$ °C for DS2003T		20	100	
V_{F}	Clamp Diode Forward Voltage	I _F = 350mA (Figure 13)		1.7	2.0	V

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Typical Performance Characteristics





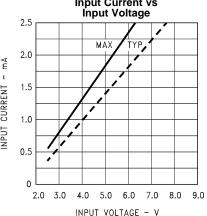
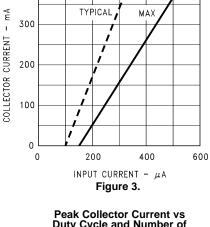


Figure 4.

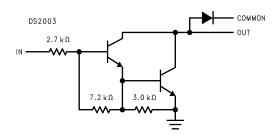
Collector Current vs Input Current 400 TYPICAL МA MAX 300



Peak Collector Current vs Duty Cycle and Number of Outputs (N16E Package) 400 2 ALLOWABLE PEAK COLLECTOR CURRENT 300 NUMBER OF OUTPUTS 200 CONDUCTING SIMULTANEOUSLY = 70°C 20 40 60 80 100 DUTY CYCLE - % Figure 5.



EQUIVALENT CIRCUITS



Test Circuits

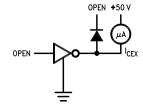


Figure 6.

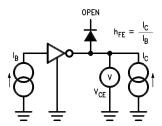


Figure 8.

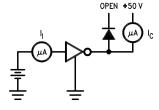


Figure 10.

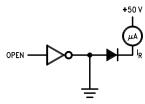


Figure 12.

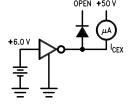


Figure 7.

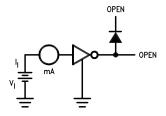


Figure 9.

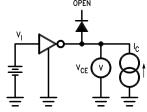


Figure 11.

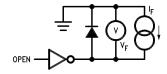


Figure 13.



Typical Applications

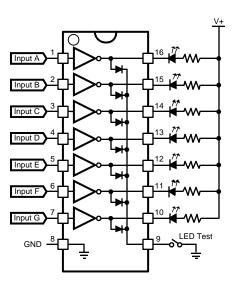


Figure 14. Typical LED Driver

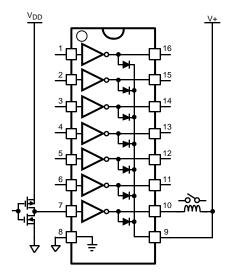


Figure 15. Typical Relay Driver

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REVISION HISTORY

CI	hanges from Revision I (April 2013) to Revision J	Pag	јe
•	Changed layout of National Data Sheet to TI format		6

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24-Aug-2018

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
DS2003CM	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	-40 to 85	DS2003CM	
DS2003CM/NOPB	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	-40 to 85	DS2003CM	
DS2003CMX/NOPB	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	-40 to 85	DS2003CM	
DS2003TM	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	-40 to 125	DS2003TM	
DS2003TM/NOPB	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	-40 to 125	DS2003TM	
DS2003TMX	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	-40 to 125	DS2003TM	
DS2003TMX/NOPB	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	-40 to 125	DS2003TM	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

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(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

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- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

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D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



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